

ABSTRACT

5 An epoxy resin molding material for sealing which comprises an epoxy resin, an epoxy resin curing agent, and a pitch, as well as an electronic component comprising an element that is sealed with the molding material. This molding material exhibits favorable coloring properties, and even when used in packages with narrow distances between pads or wires, shorting defects caused by conductive materials can be prevented, as the molding material contains no conductive carbon black.